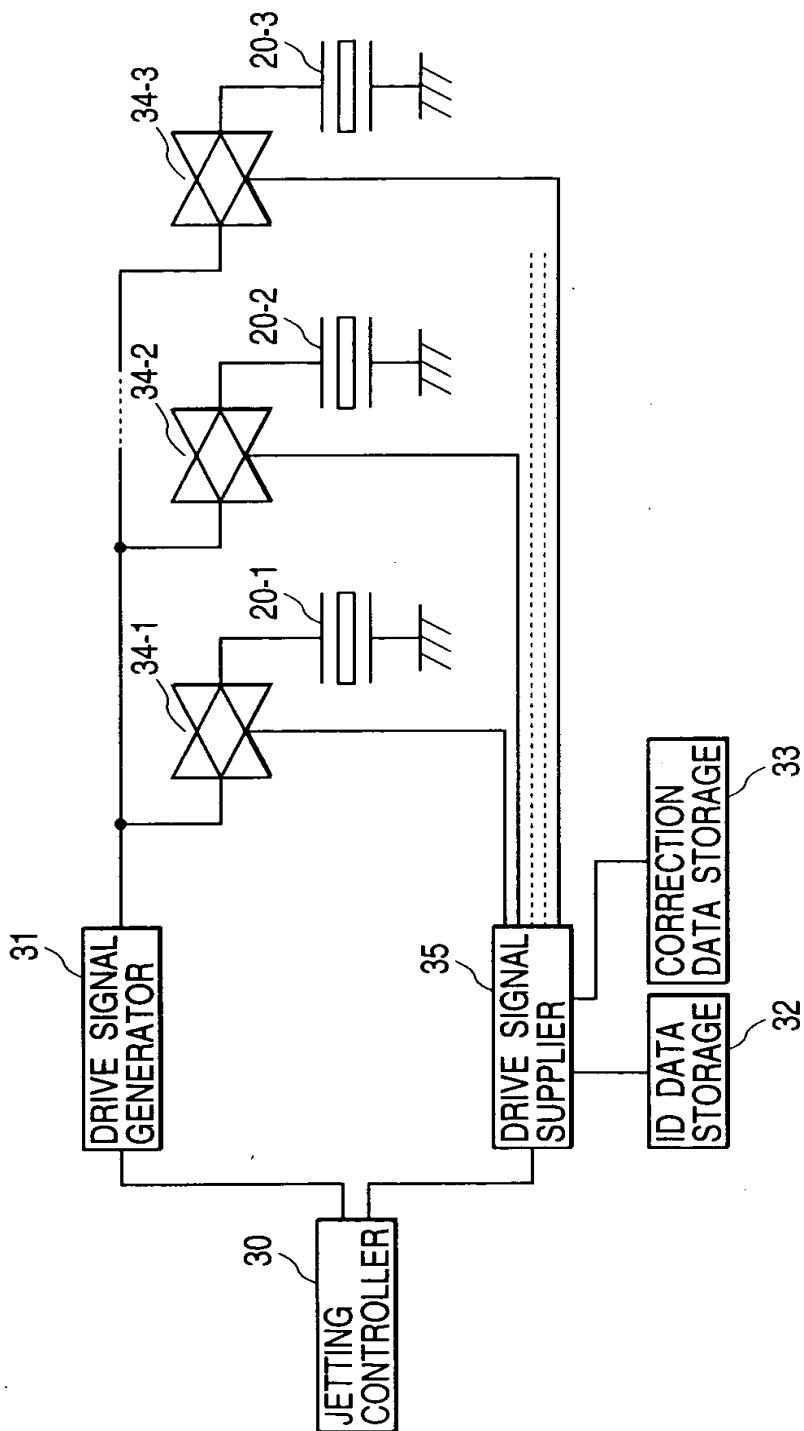


This diagram shows an exploded perspective view of a card assembly 14 and a device 19. The card assembly 14 consists of three stacked layers: a top layer 10 with a pattern of small holes 11, a middle layer 12 with a series of vertical slots, and a bottom layer 13. The device 19 is a rectangular block with two slots 20 on its top surface, designed to receive the card assembly. A small circular feature 22 is also visible on the top surface of the device.

3 / 12

FIG. 3



4 / 12

FIG. 4

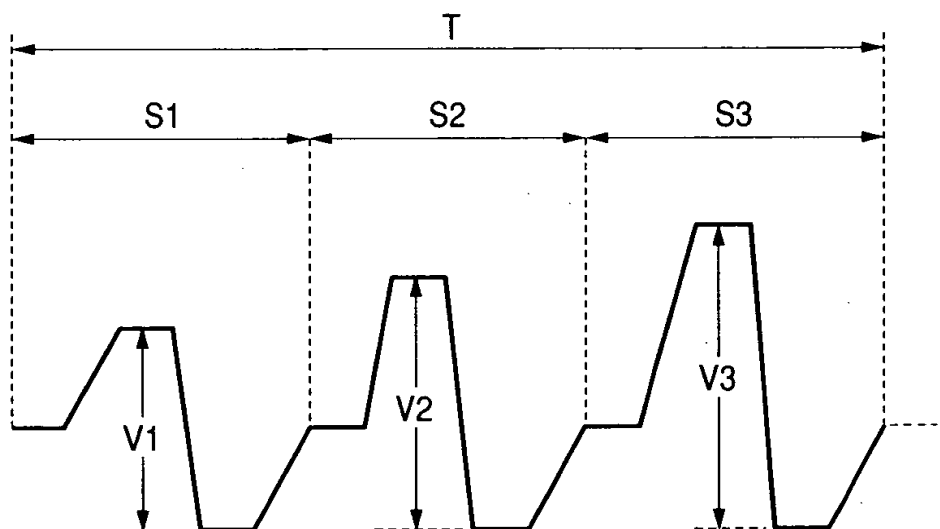
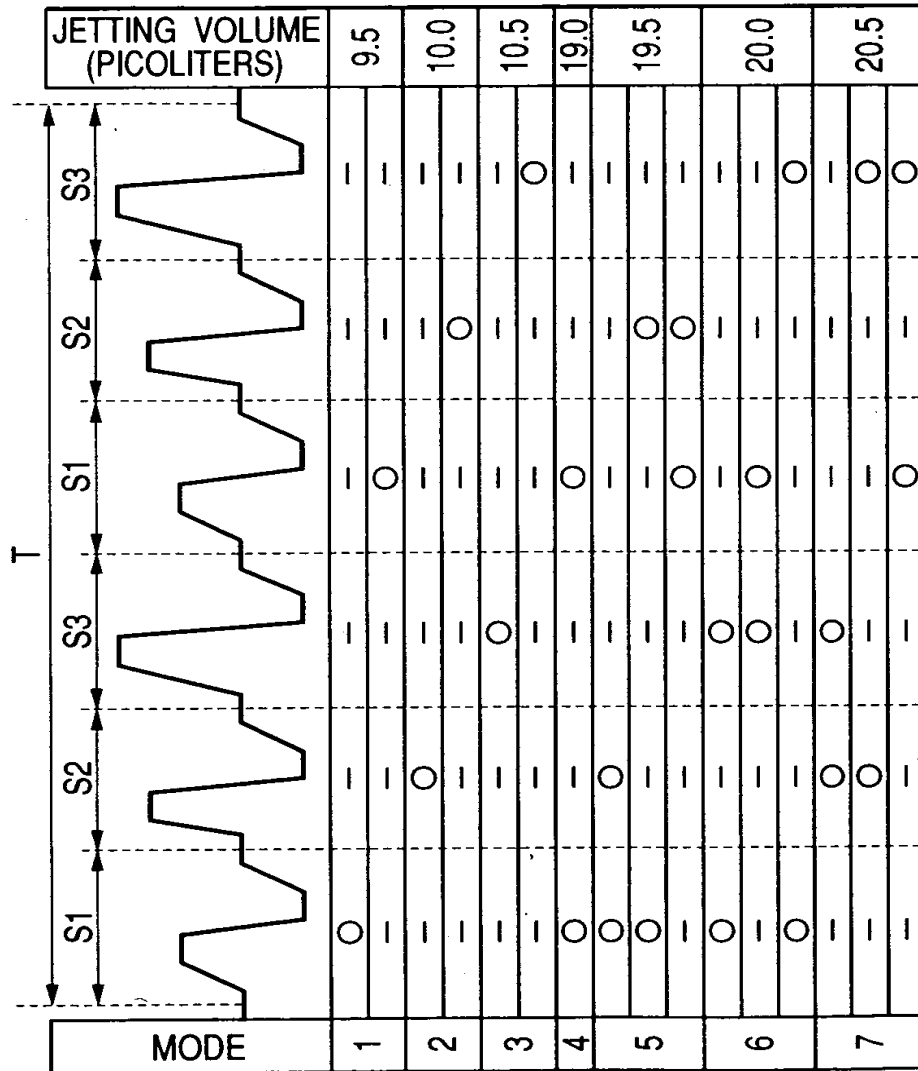
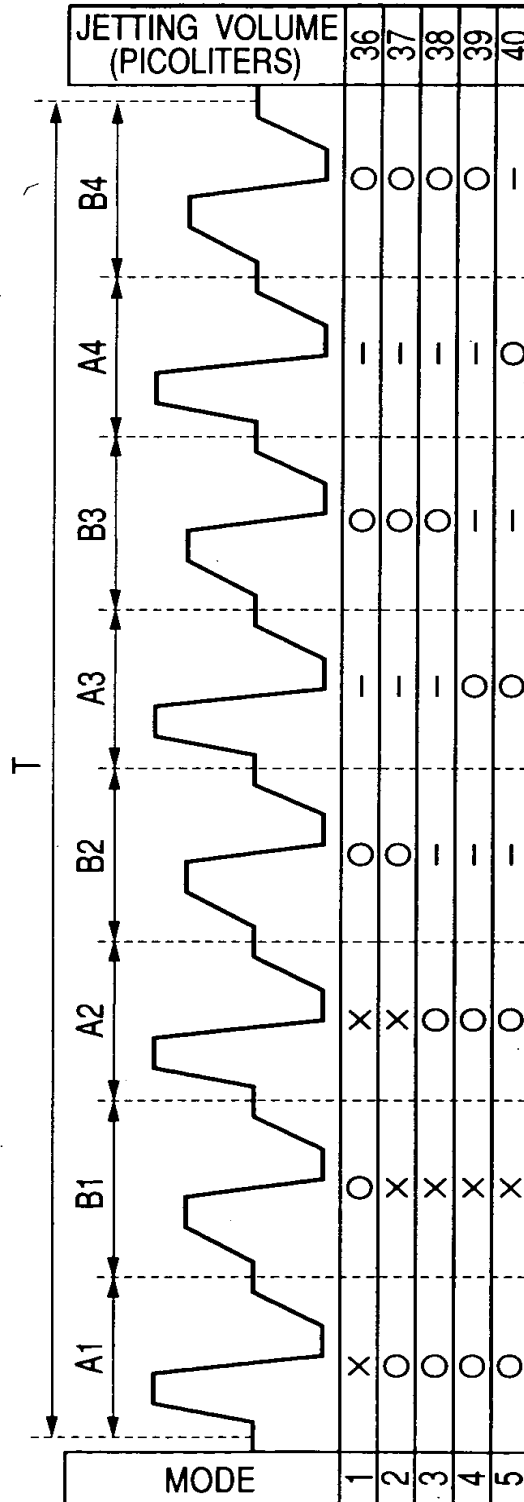


FIG. 5



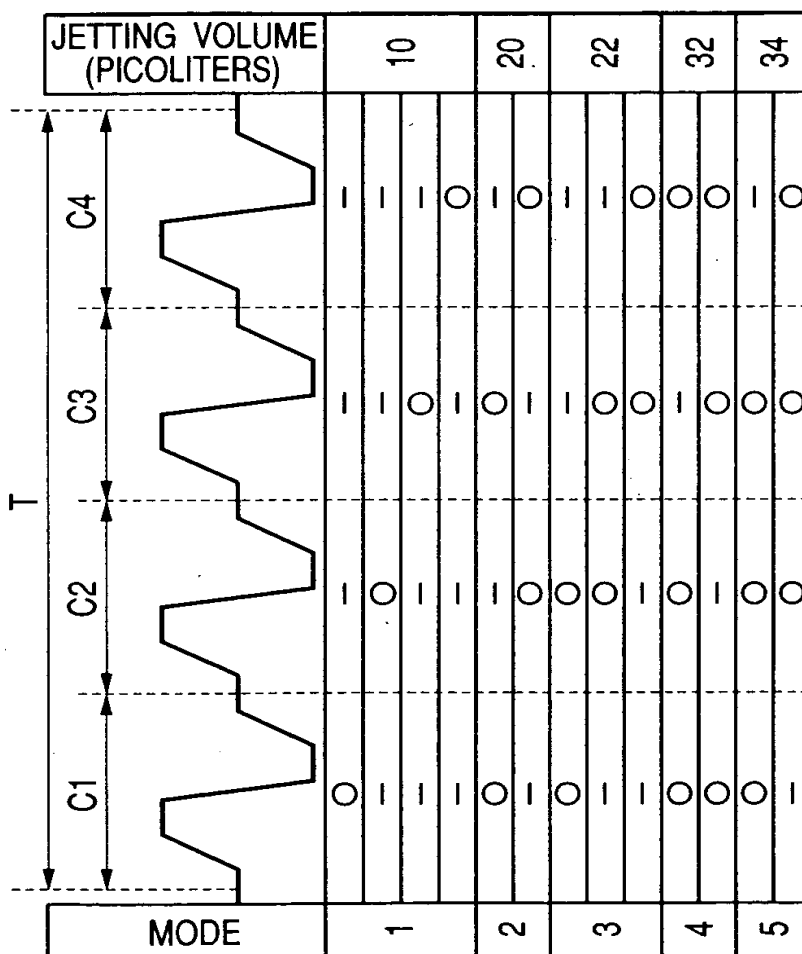
6/12

FIG. 6



7 / 12

FIG. 7



8 / 12

FIG. 8A

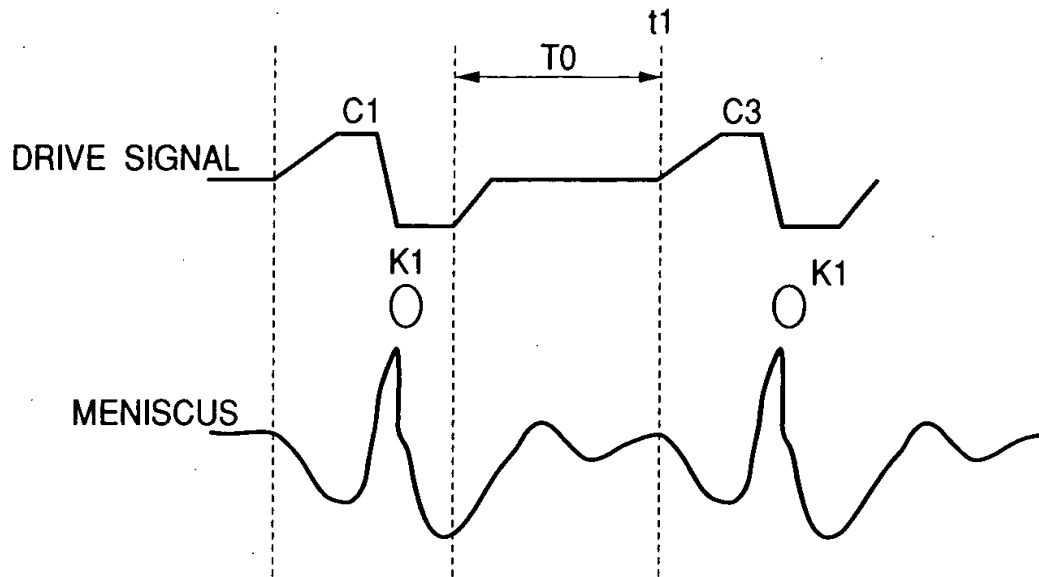
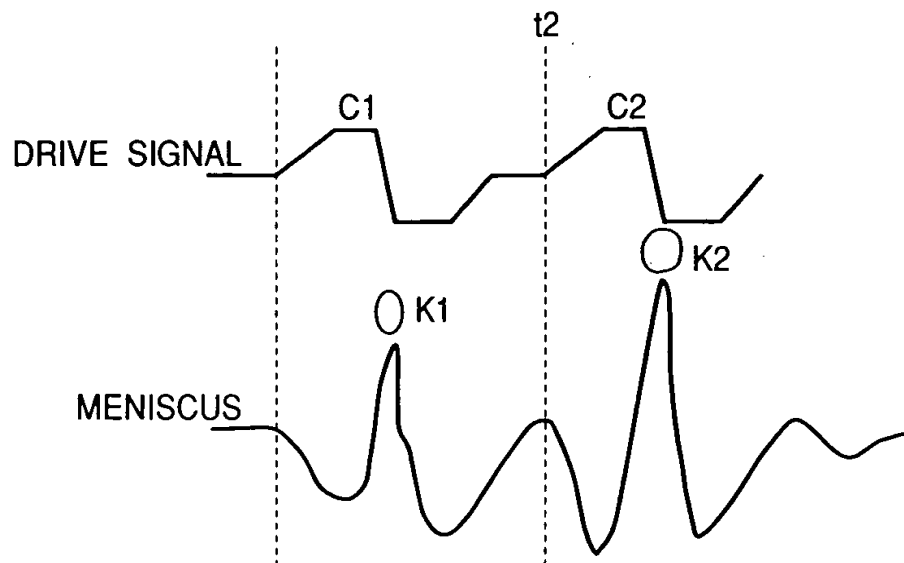
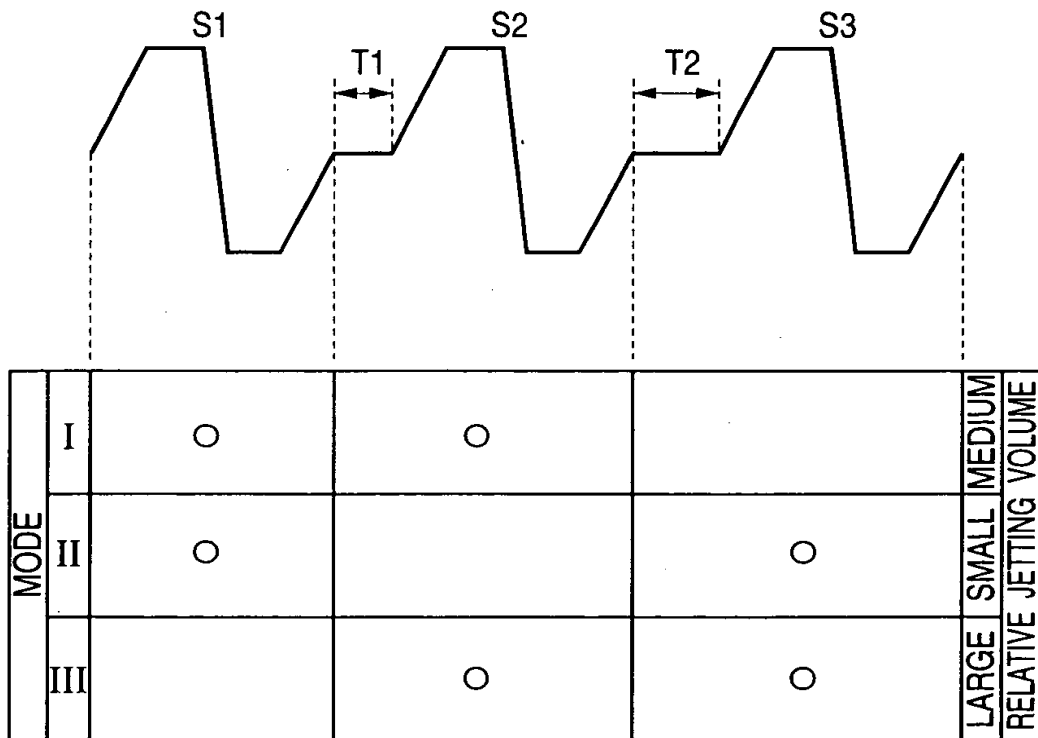


FIG. 8B



9 / 12

FIG. 9



10 / 12

FIG. 10A

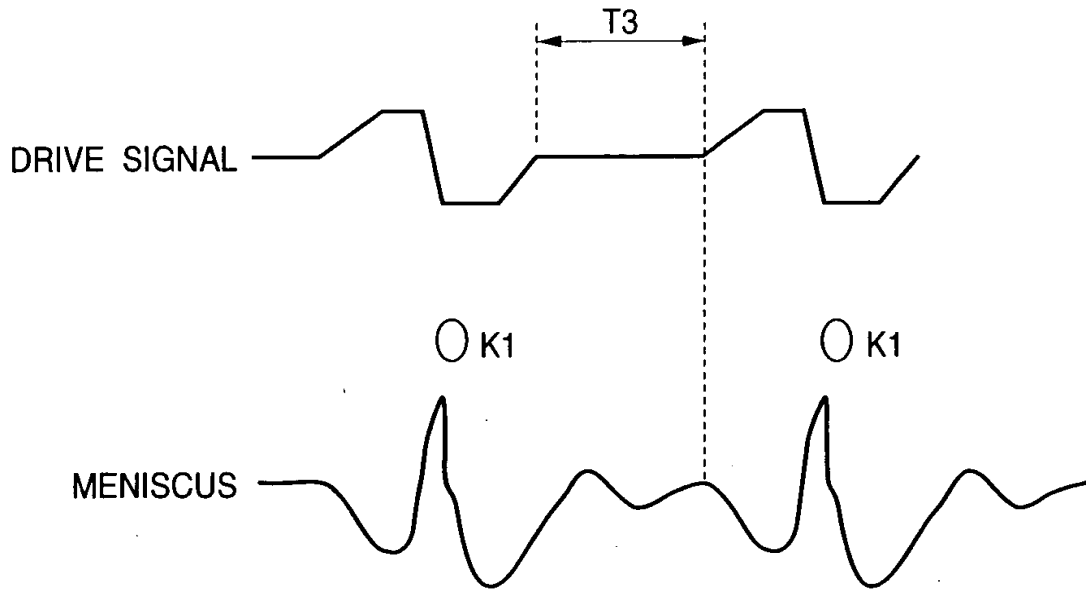
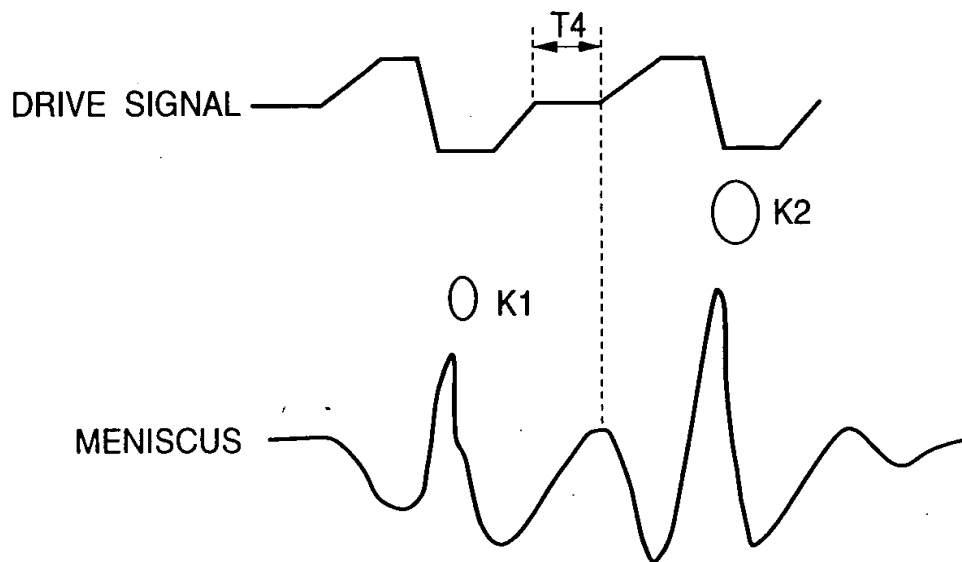


FIG. 10B



11 / 12

FIG. 11A

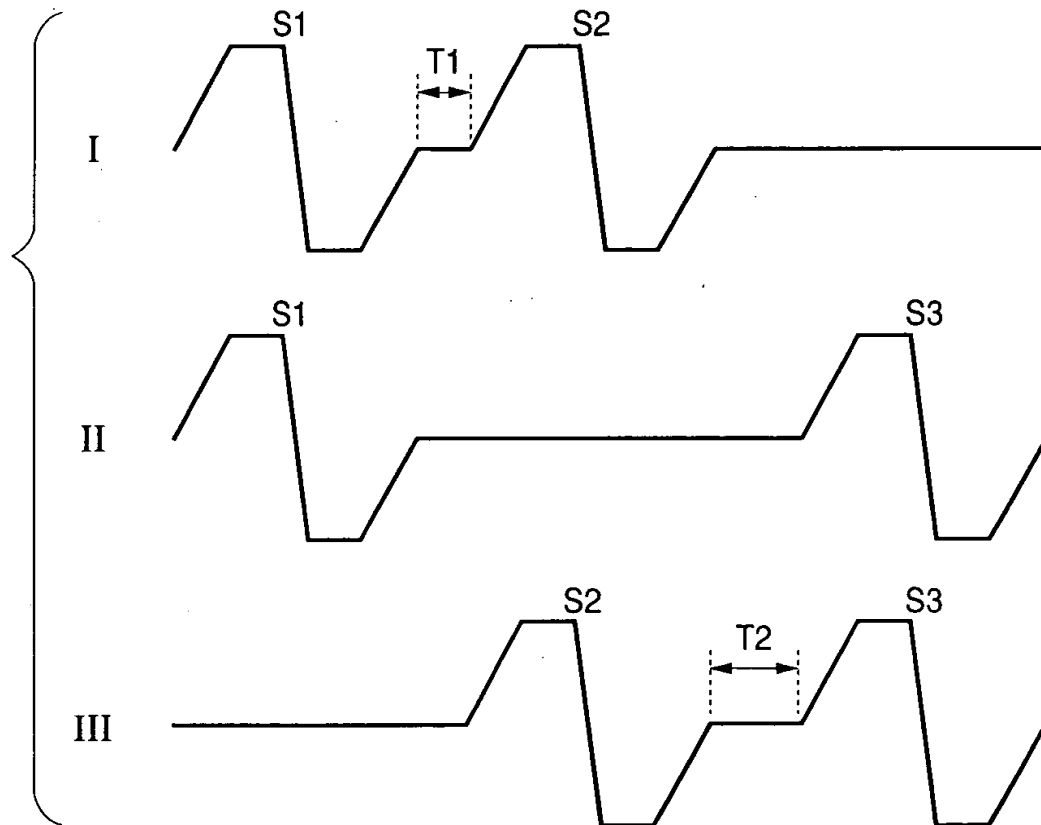
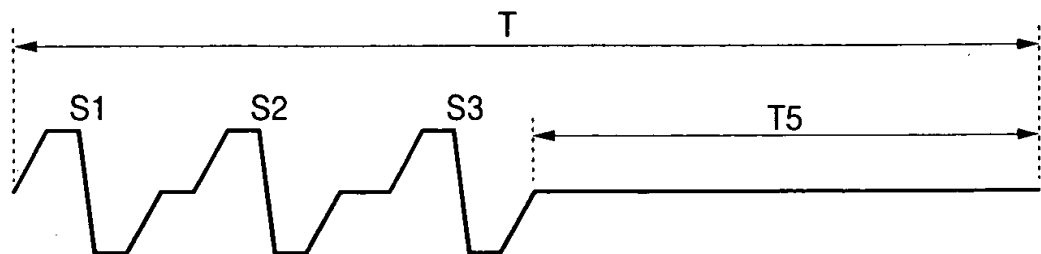


FIG. 11B



12 / 12

FIG. 12A

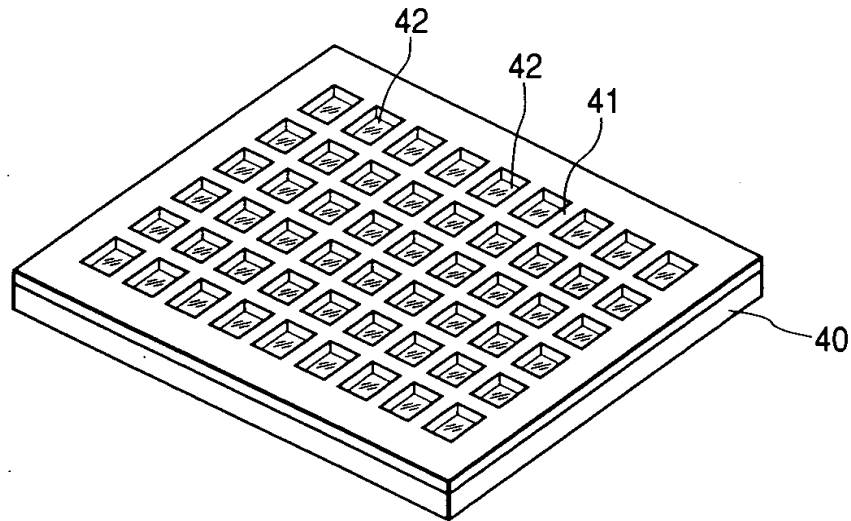


FIG. 12B

